



**ALPHA & OMEGA**  
SEMICONDUCTOR

**AO7408**

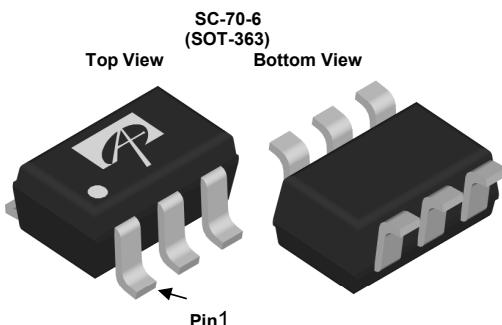
**20V N-Channel MOSFET**

### General Description

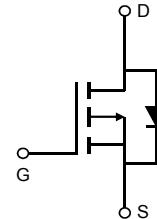
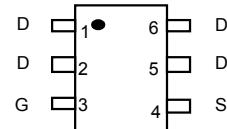
The AO7408 uses advanced trench technology to provide excellent RDS(ON), low gate charge and operation with gate voltages as low as 1.8V. This device is suitable for use as a load switch or in PWM applications.

### Product Summary

$V_{DS}$	20V
$I_D$ (at $V_{GS}=10V$ )	2A
$R_{DS(ON)}$ (at $V_{GS}=4.5V$ )	< 62mΩ
$R_{DS(ON)}$ (at $V_{GS}=2.5V$ )	< 75mΩ
$R_{DS(ON)}$ (at $V_{GS}=1.8V$ )	< 85mΩ



Top View



### Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

Parameter	Pin 1	Symbol	Maximum	Units
Drain-Source Voltage		$V_{DS}$	20	V
Gate-Source Voltage		$V_{GS}$	$\pm 8$	V
Continuous Drain Current	$T_A=25^\circ C$	$I_D$	2	A
Continuous Drain Current	$T_A=70^\circ C$		1.5	
Pulsed Drain Current <sup>C</sup>		$I_{DM}$	16	
Power Dissipation <sup>B</sup>	$T_A=25^\circ C$	$P_D$	0.35	W
	$T_A=70^\circ C$		0.22	
Junction and Storage Temperature Range		$T_J, T_{STG}$	-55 to 150	°C

### Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient <sup>A</sup> $t \leq 10s$	$R_{\theta JA}$	300	360	°C/W
Maximum Junction-to-Ambient <sup>A,D</sup> Steady-State		340	425	°C/W
Maximum Junction-to-Lead	$R_{\theta JL}$	280	320	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>STATIC PARAMETERS</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$	20			V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=20\text{V}, V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$			1 5	$\mu\text{A}$
$I_{GSS}$	Gate-Body leakage current	$V_{DS}=0\text{V}, V_{GS}=\pm 8\text{V}$			$\pm 100$	nA
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	0.4	0.7	1	V
$I_{D(\text{ON})}$	On state drain current	$V_{GS}=4.5\text{V}, V_{DS}=5\text{V}$	16			A
$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance	$V_{GS}=4.5\text{V}, I_D=2\text{A}$ $T_J=125^\circ\text{C}$		50 70	62 90	$\text{m}\Omega$
		$V_{GS}=2.5\text{V}, I_D=1.8\text{A}$		56	75	$\text{m}\Omega$
		$V_{GS}=1.8\text{V}, I_D=1\text{A}$		66	85	$\text{m}\Omega$
$g_{FS}$	Forward Transconductance	$V_{DS}=5\text{V}, I_D=2\text{A}$		15		S
$V_{SD}$	Diode Forward Voltage	$I_S=1\text{A}, V_{GS}=0\text{V}$		0.7	1	V
$I_S$	Maximum Body-Diode Continuous Current				0.35	A
<b>DYNAMIC PARAMETERS</b>						
$C_{iss}$	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=10\text{V}, f=1\text{MHz}$		260	320	pF
$C_{oss}$	Output Capacitance			48		pF
$C_{rss}$	Reverse Transfer Capacitance			27		pF
$R_g$	Gate resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$		3	4.5	$\Omega$
<b>SWITCHING PARAMETERS</b>						
$Q_g$	Total Gate Charge	$V_{GS}=4.5\text{V}, V_{DS}=10\text{V}, I_D=2\text{A}$		2.9	4	nC
$Q_{gs}$	Gate Source Charge			0.4		nC
$Q_{gd}$	Gate Drain Charge			0.6		nC
$t_{D(\text{on})}$	Turn-On DelayTime	$V_{GS}=10\text{V}, V_{DS}=10\text{V}, R_L=5\Omega, R_{\text{GEN}}=3\Omega$		2.5		ns
$t_r$	Turn-On Rise Time			3.2		ns
$t_{D(\text{off})}$	Turn-Off DelayTime			21		ns
$t_f$	Turn-Off Fall Time			3		ns
$t_{rr}$	Body Diode Reverse Recovery Time	$I_F=2\text{A}, dI/dt=100\text{A}/\mu\text{s}$		14	19	ns
$Q_{rr}$	Body Diode Reverse Recovery Charge	$I_F=2\text{A}, dI/dt=100\text{A}/\mu\text{s}$		3.8		nC

A. The value of  $R_{\text{gJA}}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^\circ\text{C}$ . The value in any given application depends on the user's specific board design.

B. The power dissipation  $P_D$  is based on  $T_{J(\text{MAX})}=150^\circ\text{C}$ , using  $\leq 10\text{s}$  junction-to-ambient thermal resistance.

C. Repetitive rating, pulse width limited by junction temperature  $T_{J(\text{MAX})}=150^\circ\text{C}$ . Ratings are based on low frequency and duty cycles to keep initial  $T_J=25^\circ\text{C}$ .

D. The  $R_{\text{gJA}}$  is the sum of the thermal impedance from junction to lead  $R_{\text{gUL}}$  and lead to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using <300 $\mu\text{s}$  pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-ambient thermal impedance which is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, assuming a maximum junction temperature of  $T_{J(\text{MAX})}=150^\circ\text{C}$ . The SOA curve provides a single pulse rating.

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## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

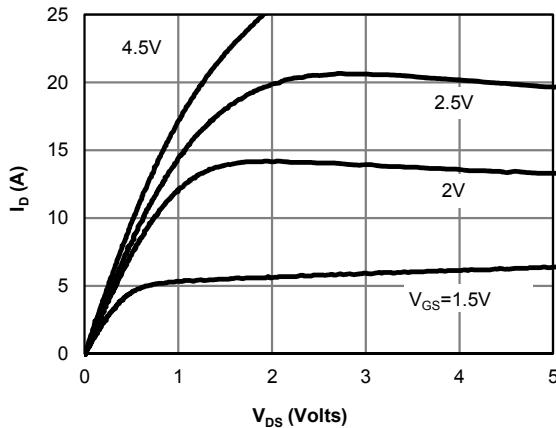


Fig 1: On-Region Characteristics (Note E)

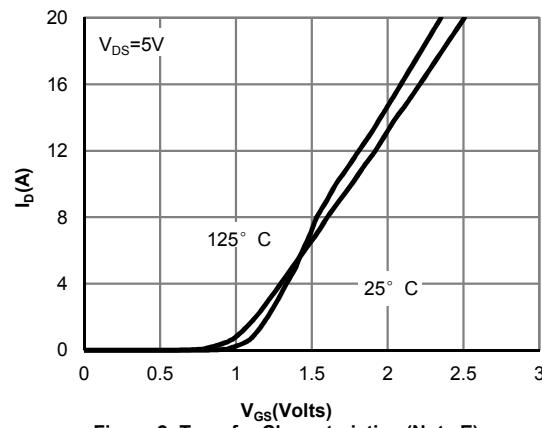


Figure 2: Transfer Characteristics (Note E)

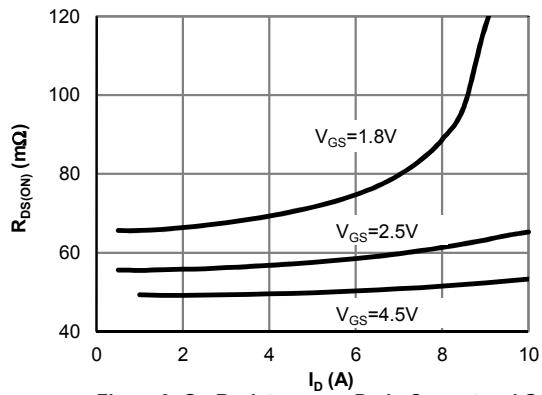


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

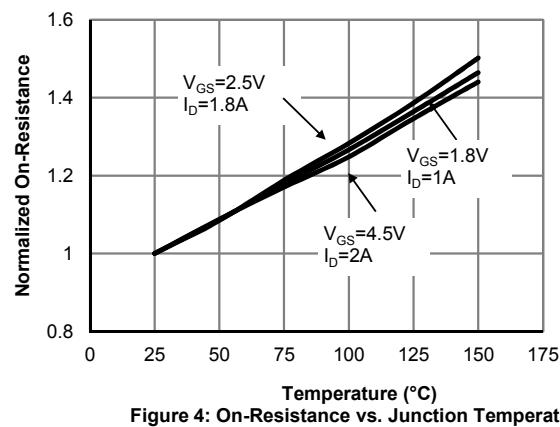


Figure 4: On-Resistance vs. Junction Temperature (Note E)

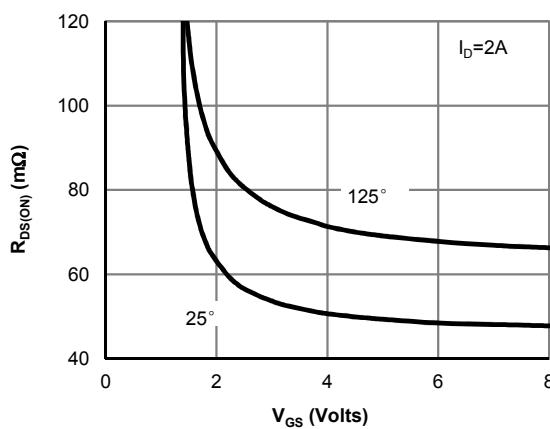


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

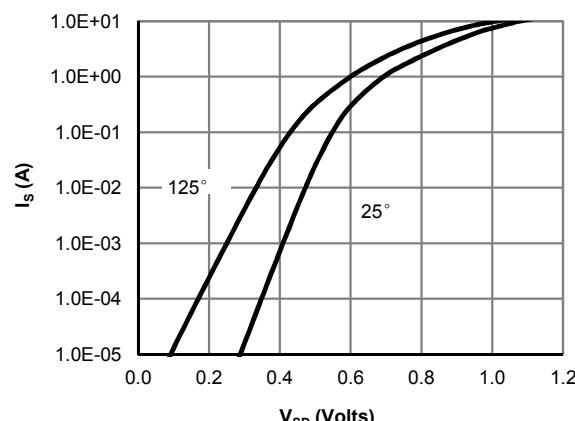


Figure 6: Body-Diode Characteristics (Note E)

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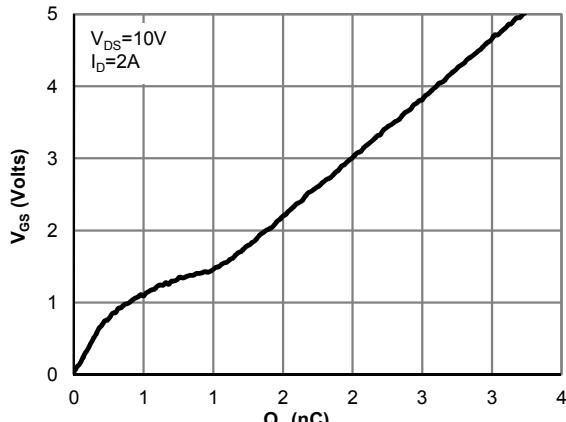


Figure 7: Gate-Charge Characteristics

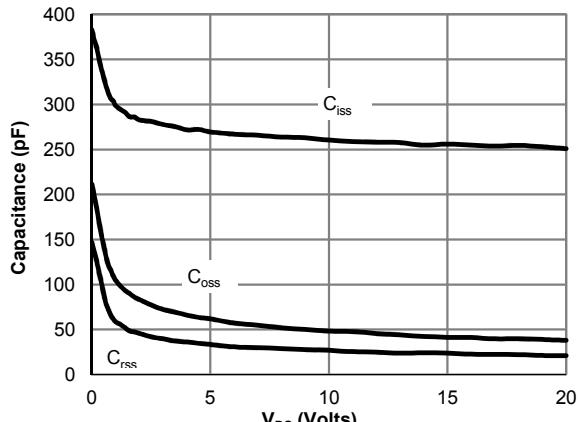


Figure 8: Capacitance Characteristics

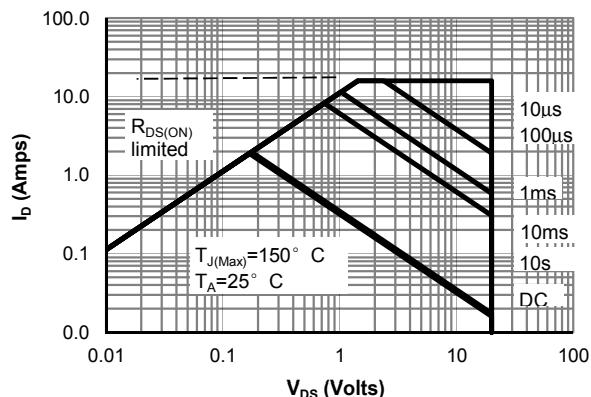


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

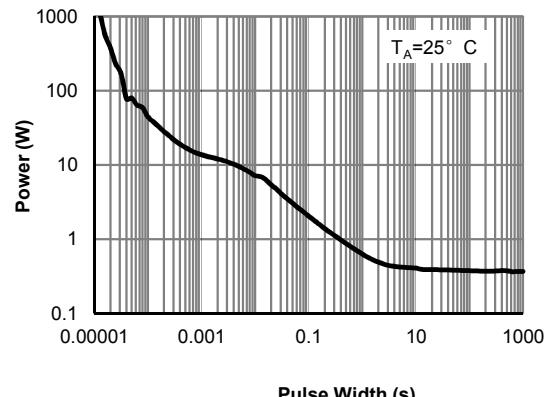


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note F)

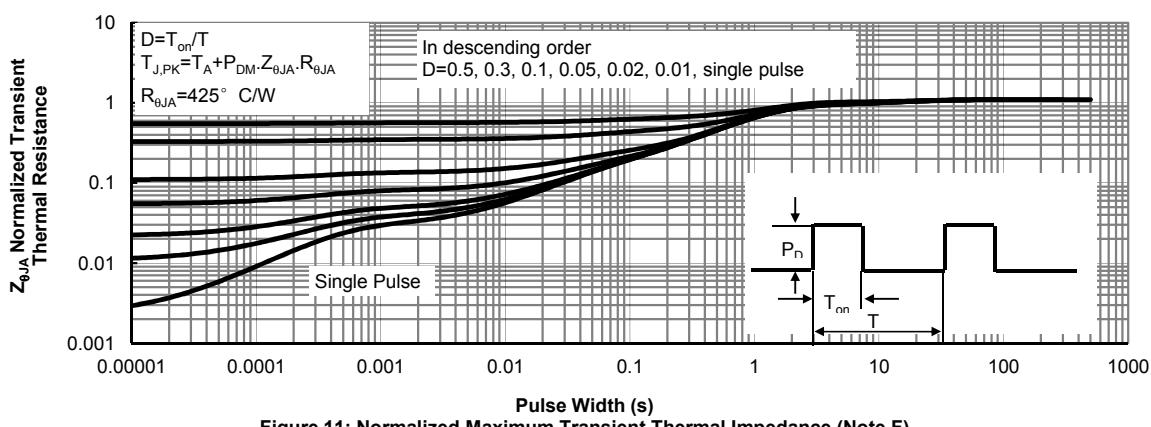
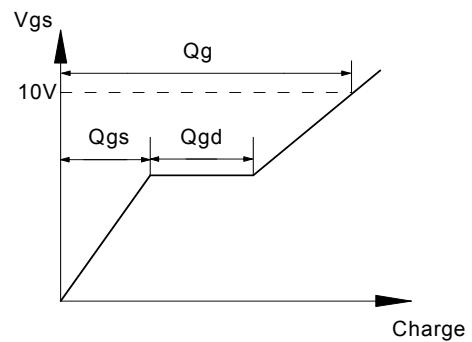
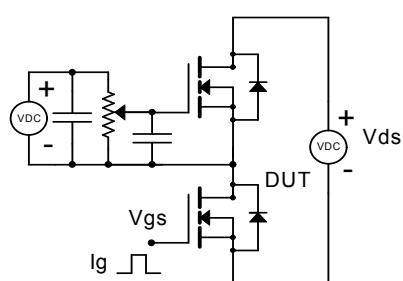
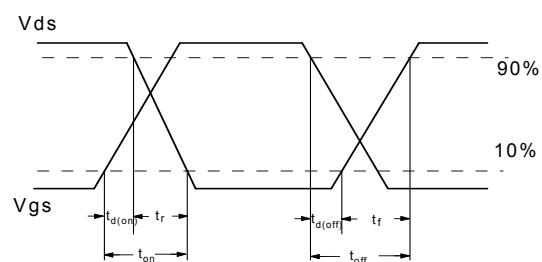
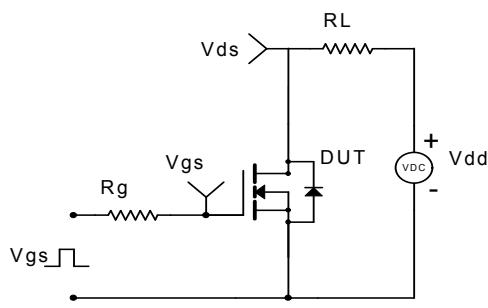


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

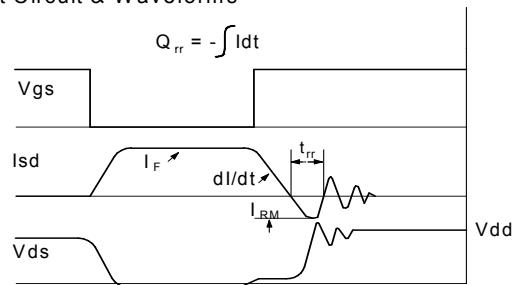
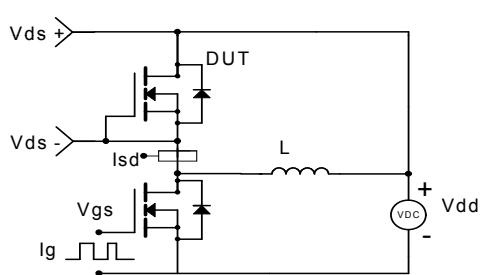
### Gate Charge Test Circuit & Waveform



### Resistive Switching Test Circuit & Waveforms



### Diode Recovery Test Circuit & Waveforms



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